

KB-3151C (ANSI: FR-1/JIS: PP7F)**覆铜箔酚醛树脂纸基层压板****特点**

- 在高温下弓曲率、扭曲率小于 1.0%
- 高耐漏电起痕指数 (600 伏以上, 需提出特殊要求)
- 适合之冲孔温度为 40~70℃

Features

- In high temperature warpage and twist both less than 1.0%
- High CTI Value (CTI Over 600V need special request)
- Suitable for punching at 40~70℃

General Properties 一般特性

Test Item 测试项目	Unit 单位	Test Condition 处理条件	Testing Method 测试方法	Specification 规格值	Typical Value 典型值
Solder Resistance 耐焊性 (float 260℃)	Sec	A	JIS C 6481	≥10	20~30
Heat Resistance 耐热性	—	190℃ 30min	JIS C 6481	190℃ 30min 无异常	200℃ 30min 无异常
Peel Strength (Copper Foil 35 μm) 铜箔剥离强度 (35 μm 铜箔)	kgf/cm	A float 260℃/10Sec	JIS C 6481	≥1.2	1.8~2.1 1.8~2.1
Flexural Strength 弯曲强度	Lengthwise 纵向	A	JIS C 6481	≥8	14-16
	Crosswise 横向			≥8	13-14
Volume Resistivity 体积阻抗系数	Ω-cm	C-96/20/65 C-96/20/65+C-96/40/90	JIS C 6481	5×10 ⁹ 5×10 ⁸	1.0×10 ¹² ~10 ¹³ 1.0×10 ¹² ~10 ¹³
Surface Resistivity 表面抗阻	Adhesive Side 粘接剂面	C-96/20/65 C-96/20/65+C-96/40/90	JIS C 6481	1×10 ¹⁰ 1×10 ⁹	1.0×10 ¹¹ ~10 ¹² 1.0×10 ¹⁰ ~10 ¹¹
	Laminate Side 积层板面	C-96/20/65 C-96/20/65+C-96/40/90		1×10 ⁹ 1×10 ⁷	1.0×10 ¹⁰ ~10 ¹¹ 1.0×10 ⁹ ~10 ¹⁰
Insulation Resistance 绝缘抗阻	Ω	C-96/20/65 C-96/20/65+D-2/100	JIS C 6481	1×10 ⁹ 1×10 ⁶	1.0×10 ¹¹ ~10 ¹² 1.0×10 ⁸ ~10 ⁹
Chemical Resistance 耐化学性	—	3% NaOH 40℃ 3min 3%氢氧化钠 40℃ 3 分钟	JIS C 6481	No Change 无异常	No Change 无异常
		Boiled in trichloroethylene for 3 min 三氯乙烯中煮沸 3 分钟	JIS C 6481	No Change 无异常	No Change 无异常
Moisture Absorption 吸水率	%	E-24/50+D-24/23	JIS C 6481	≤2	0.8~1.0
Flammability 阻燃性	Rating	A	UL94	UL94 V-0	V-0
Dielectric Constant (1 MHz) 介电常数 (1 MHz)	—	C-96/20/65	JIS C 6481	≤5.5	4.0~5.0
		C-96/20/65+D-24/23		≤6.0	4.5~5.5
Dissipation Factor 介质损耗因子	—	C-96/20/65	JIS C 6481	≤0.05	0.025~0.035
		C-96/20/65+D-24/23		≤0.1	0.045~0.055
CTI Value CTI 值	V	0.1% NH ₄ CL	IEC 60112	≥175 ≥600	175 600
Punching Temperature 冲孔温度	℃	A	GB/T4722	40-70	40-70

Remarks: Typical values for reference only 注: 典型值仅作参考 Stand values according to JIS-C-6485 规格值参照 JIS-C-6485

A = Keep the specimen originally without any process 保持原样, 不作处理

C = Temperature and humidity conditioning 在恒温恒湿的空气中处理

D = Immersing in distilled water with temperature control. 浸在恒温的水中处理

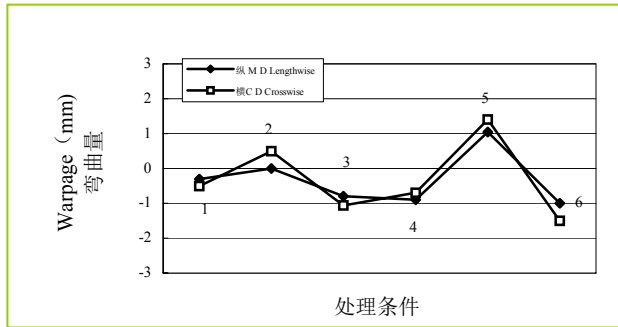
E = Temperature conditioning 在恒温的空气中处理

KB-3151C (ANSI: FR-1/JIS: PP7F)

覆铜箔酚醛树脂纸基层压板

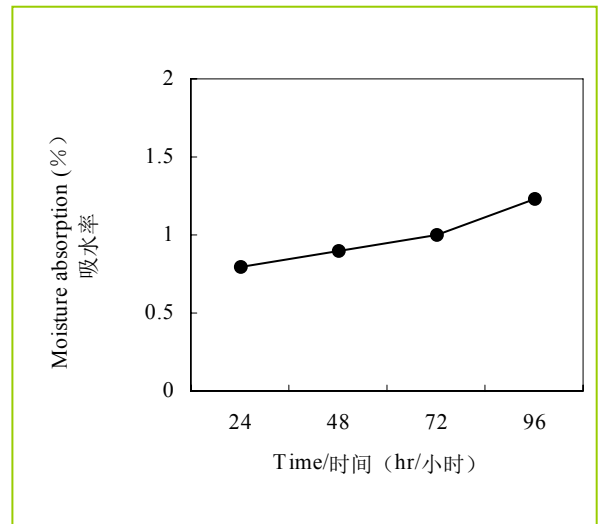
Speciality Chart 板材特性图

Warpage of PCB during processing/印制电路板加工时弯曲度(Thickness 1.6mm single side)

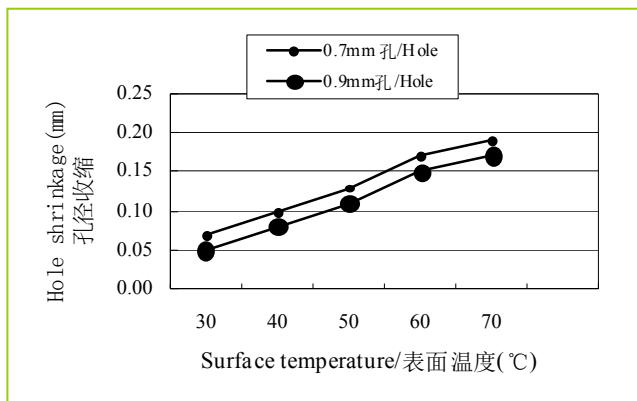


1. Feeding 投料	2. Heating at 130°C for 90 sec 130°C下加热 90 秒	3. Etching, Rinsing, Drying 蚀刻, 清洗, 烘干
4. Heating at 200°C for 30 sec 200°C下加热 30 秒	5. Punching at 50°C 50°C下冲孔	6. Soldering at 260°C for 5sec 260°C 焊锡 5 秒

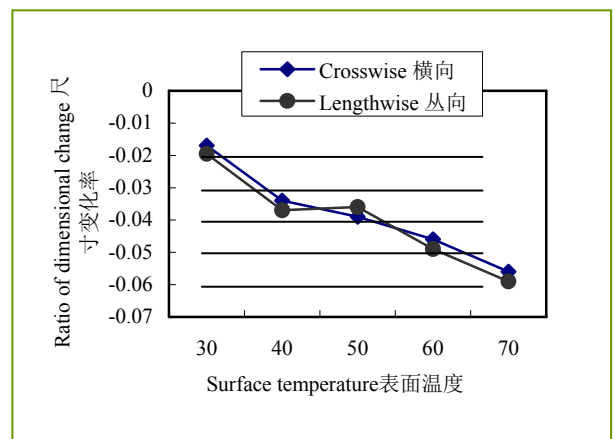
Moisture absorption 吸水率



Punched hole shrinkage
冲孔后孔径收缩



Dimensional change of punched PCB
冲孔后之尺寸变化



Purchasing Information 采购信息

Type 类型	Thickness 厚度	Copper Cladding 铜箔厚度	Regular Size (mm) 常规尺寸	CTI Value CTI 值
KB-3151C FR-1	0.8mm ~ 1.6mm	18µm 35µm 70µm	1020*1020mm (40"*40") 1020*1220mm (40"*48")	175/600V

Note: Other sheet size and thickness could be available upon request.
可根据客户要求提供其它尺寸和厚度;